NAND BGA Package Provides Up to 16 GByte Solid State Storage

Microsemi Corporation's Power and Microelectronics Group now offers a high-density Single Level Cell (SLC) NAND solid state storage solution in a single integrated plastic ball grid array (PBGA) package. In 8 and 16 GByte densities, the 27 mm x 22 mm package offers a 63% space savings over a standard CF card of comparable density. The easy-to-integrate package consumes very little battery life when compared to hard drives and other larger form factor SSD solutions, yet provides high performing data rates.

The BGA is designed specifically for use in the rugged and demanding environments of defense and aerospace applications, providing highly reliable data storage for embedded computing such as that used in aircraft, communications and missiles.

The surface-mountable data storage device supports various PATA interface protocols, and an integrated 32-bit RISC flash controller manages wear leveling, error correction and power interruption protection. The PBGA package is constructed using eutectic tin-lead solder balls on a 1.27mm pitch with strategically placed signals to extend device life in harsh environments.

Microsemi has full design, manufacture and test capabilities for a wide variety of MCPs, Commercial-Off-The-Shelf (COTS) memory, processors and combination MCPs for demanding applications at our US facilities. Additionally, these microelectronic products can be ruggedized and processed for tamper resistance.

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